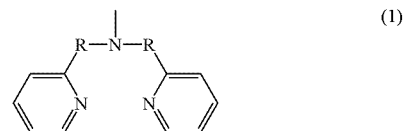




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C22C 19/05 (2006.01)(72) Inventors: **Shoichiro SAKAI**, Osaka (JP); **Ryuta OHSUKA**, Osaka (JP); **Koji NITTA**, Osaka (JP); **Yoshihito YAMAGUCHI**, Shiga (JP); **Masaharu YASUDA**, Osaka (JP); **Akira TSUCHIKO**, Osaka (JP); **Koji KASUYA**, Osaka (JP); **Kenji NISHIE**, Hyogo (JP); **Yu FUKUI**, Hyogo (JP)(52) **U.S. Cl.**
CPC **H05K 3/103** (2013.01); **C22C 19/05** (2013.01); **H05K 1/0373** (2013.01); **H05K 3/1258** (2013.01); **H05K 2201/0212** (2013.01); **H05K 2203/061** (2013.01); **H05K 2203/176** (2013.01)(57) **ABSTRACT**

In manufacturing a printed circuit board using a semi-additive method, a removal liquid that has been used in removing a nickel-chromium-containing layer (5) is regenerated by contacting the removal liquid with a chelate resin having a functional group represented by a following formula (1) :

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where a plurality of Rs are identical divalent hydrocarbon groups having 1 to 5 carbons, and a portion of hydrogen atoms may be substituted with halogen atoms.

